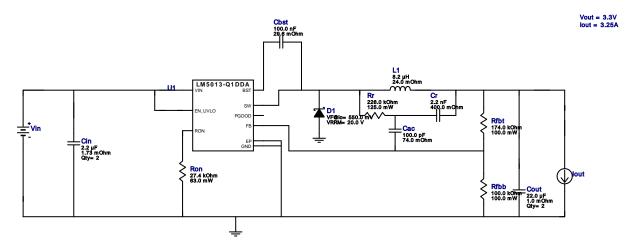
VinMin = 40.0V VinMax = 100.0V Vout = 3.3V Iout = 3.25A

Device = LM5013QDDARQ1 Topology = Buck Created = 2022-08-11 11:19:01.436 BOM Cost = \$3.73 BOM Count = 14 Total Pd = 2.74W

WEBENCH® Design Report

Design: 16 LM5013QDDARQ1 LM5013QDDARQ1 40V-100V to 3.3V @ 3.25A



Design Alerts

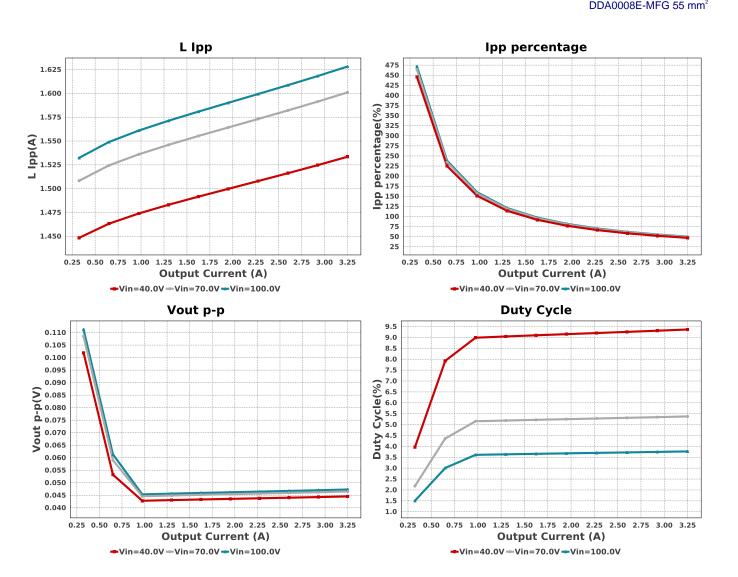
Component Selection Information

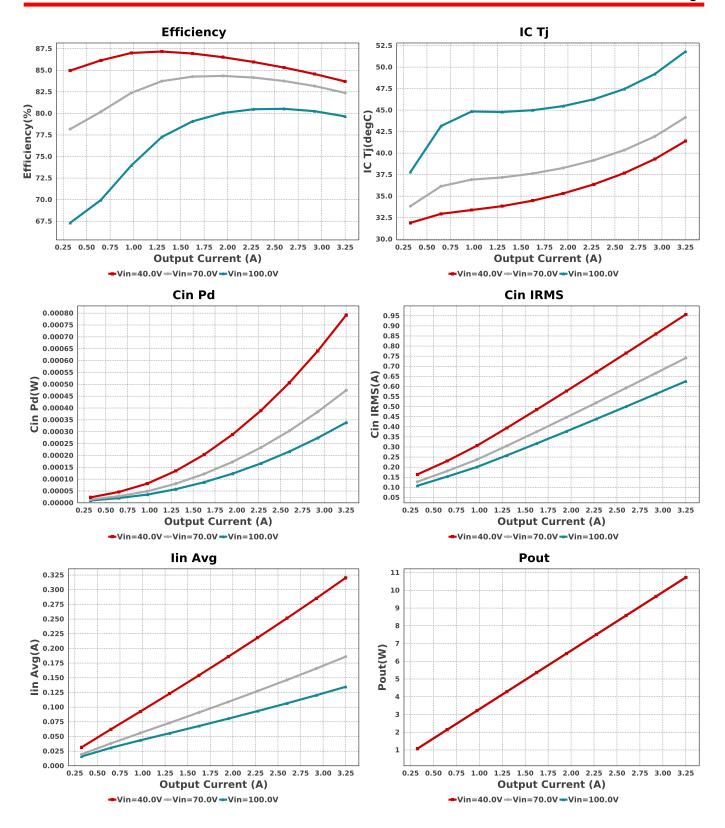
The LM5013-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application.

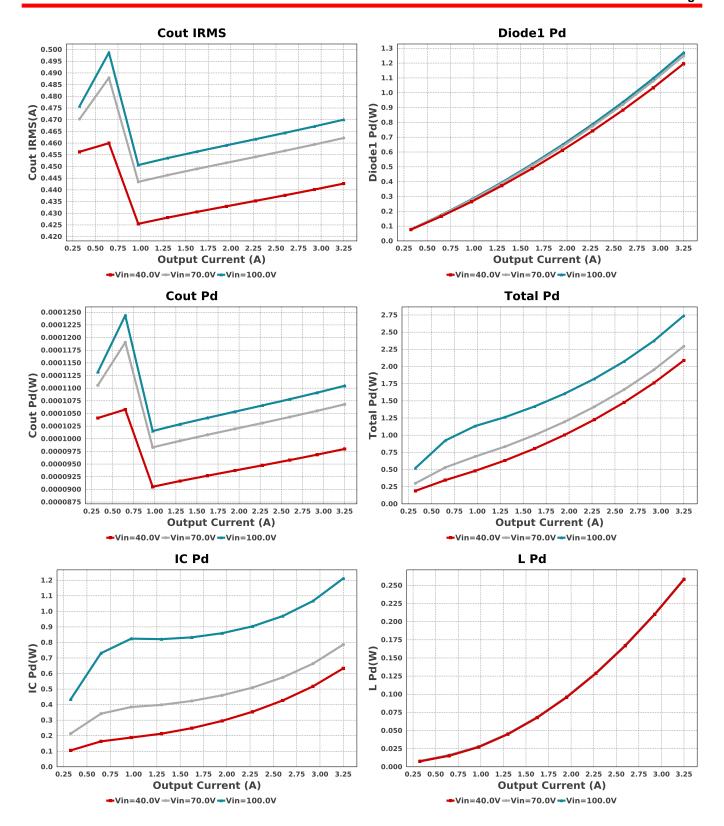
Electrical BOM

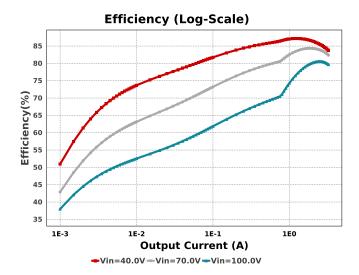
Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cac	Kemet	C0805C101K5GACTU Series= C0G/NP0	Cap= 100.0 pF ESR= 74.0 mOhm VDC= 50.0 V IRMS= 524.0 mA	1	\$0.01	0805 7 mm ²
Cbst	TDK	CGA3E2X7R1H104K080AA Series= X7R	Cap= 100.0 nF ESR= 29.6 mOhm VDC= 50.0 V IRMS= 971.99 mA	1	\$0.01	0603 5 mm ²
Cin	TDK	C3225X7R2A225K230AB Series= X7R	Cap= 2.2 uF ESR= 1.73 mOhm VDC= 100.0 V IRMS= 5.5932 A	2	\$0.21	1210_250 15 mm ²
Cout	MuRata	GRM188R60J226MEA0D Series= X5R	Cap= 22.0 uF ESR= 1.0 mOhm VDC= 6.3 V IRMS= 6.0 A	2	\$0.05	0603 5 mm ²
Cr	Kemet	C0805C222K5RACTU Series= X7R	Cap= 2.2 nF ESR= 400.0 mOhm VDC= 50.0 V IRMS= 251.0 mA	1	\$0.01	0805 7 mm ²
D1	Comchip Technology	CDBC520-G	VF@Io= 550.0 mV VRRM= 20.0 V	1	\$0.18	SMC 83 mm ²
L1	Coilcraft	XAL6060-822MEB	L= 8.2 μH 24.0 mOhm	1	\$0.82	XAL6060 72 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rfbb	Vishay-Dale	CRCW0603100KFKEA Series= CRCWe3	Res= 100.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²
Rfbt	Yageo	RC0603FR-07174KL Series= ?	Res= 174.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	0603 5 mm ²
Ron	Vishay-Dale	CRCW040227K4FKED Series= CRCWe3	Res= 27.4 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	0402 3 mm ²
Rr	Panasonic	ERJ-6ENF2263V Series= ERJ-6E	Res= 226.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	0805 7 mm ²
U1	Texas Instruments	LM5013QDDARQ1	Switcher	1	\$2.14	DDA0008E MEG 55 mm ²









Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	625.601 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	338.57 μW	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	470.014 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	110.47 μW	Capacitor	Output capacitor power dissipation
5.	Diode1 Pd	1.27 W	Diode	Diode1 power dissipation
6.	IC Pd	1.212 W	IC	IC power dissipation
7.	IC Tj	51.807 degC	IC	IC junction temperature
8.	IC Tolerance	19.0 mV	IC	IC Feedback Tolerance
9.	ICThetaJA	18.0 degC/W	IC	IC junction-to-ambient thermal resistance
10.	lin Avg	134.65 mA	iC	Average input current
11.	lpp percentage	50.098 %	Inductor	Inductor ripple current percentage (with respect to average inductor
	ipp porcornage	00.000 /0	madotoi	current)
12.	L lpp	1.628 A	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	258.8 mW	Inductor	Inductor power dissipation
	Cin Pd	338.54 μW	Power	Input capacitor power dissipation
1 4 . 15.	Cout Pd		Power	· · · · · · · · · · · · · · · · · · ·
		110.46 µW		Output capacitor power dissipation
16.	Diode1 Pd	1.269 W	Power	Diode1 power dissipation
17.		1.212 W	Power	IC power dissipation
18.	L Pd	258.8 mW	Power	Inductor power dissipation
19.	Total Pd	2.74 W	Power	Total Power Dissipation
20.	BOM Count	14	System	Total Design BOM count
			Information	
21.	Duty Cycle	3.769 %	System	Duty cycle
			Information	
22.	Efficiency	79.651 %	System	Steady state efficiency
			Information	
23.	FootPrint	286.0 mm ²	System	Total Foot Print Area of BOM components
			Information	
24.	Frequency	272.731 kHz	System	Switching frequency
			Information	
25.	lout	3.25 A	System	lout operating point
			Information	
26.	Mode	CCM	System	Conduction Mode
			Information	
27.	Pout	10.725 W	System	Total output power
			Information	
28.	Total BOM	\$3.732	System	Total BOM Cost
_0.	rotal Botti	ψο σ2	Information	rotal Both Goot
29.	Vin	100.0 V	System	Vin operating point
20.	VIII	100.0 V	Information	viii operating point
30.	Vout	3.3 V	System	Operational Output Voltage
30.	vout	3.3 V	•	Operational Output Voltage
24	Vout Actual	2 200 \/	Information	Vout Actual calculated based on calcuted voltage divider registers
31.	Vout Actual	3.288 V	System	Vout Actual calculated based on selected voltage divider resistors
00	March Talamana	0.007.0/	Information	Vest Television has a local or 10 Television (as less flore)
32.	Vout Tolerance	2.887 %	System	Vout Tolerance based on IC Tolerance (no load) and voltage divide
			Information	resistors if applicable
33.	Vout p-p	47.295 mV	System	Peak-to-peak output ripple voltage
			Information	

Design Inputs

Name	Value	Description	
lout	3.25	Maximum Output Current	
VinMax	100.0	Maximum input voltage	
VinMin	40.0	Minimum input voltage	
Vout	3.3	Output Voltage	
base_pn	LM5013-Q1	Base Product Number	
source	DC	Input Source Type	
Та	30.0	Ambient temperature	

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of Cin and Cout, and the inductance and DC resistance of L1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

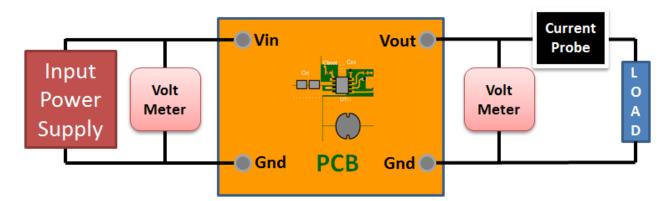
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab town to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 40.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to Vin and GND. Connect a digital volt meter and a load if needed to set the minimum lout of the design from Vout and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between Vin and GND, a load is connected between Vout and GND and a current meter is connected in series between Vout and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

- 1. The LM5013-Q1 is qualified for Automotive applications. All passives and other components selected in this design may not be qualified for Automotive applications. The user is required to verify that all components in the design meet the qualification and safety requirements for their specific application
- 2. Master key: DB27146014BCE25D[v1]
- 3. LM5013-Q1 Product Folder: http://www.ti.com/product/LM5013%2DQ1: contains the data sheet and other resources.

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